



Schedule of Scope to Certificate of Approval Component Capability Approval

IECQ Certificate No.: IECQ-C BSI 15.0002

CB Certificate No.: E039/CA

Schedule Number: IECQ-C BSI 15.0002-S Rev No.: 11 Revision Date: 2015/05/16 Page 1 of 2

Board Types:	Rigid single and double-sided with plain holes	BS 123100-003
	Rigid double-sided with plated-through holes	BS 123200-003
	Rigid multi-layer	BS 123300-003
	Flexible single and double sided without-through connections	BS 123400-003
	Flexible double-sided with through-connections	BS 123500-003
	Flex-rigid multi-layer with through-connections	BS 123600-003
Base Materials:	Epoxide Woven Glass Polyimide Film	
Board Size:	610 mm x 457 mm Maximum	BS EN 123 300
	610 mm x 457 mm Maximum	BS EN 123 100, BS EN 123 200
	610 mm x 457 mm Maximum	BS EN 123 400, BS EN 123 500
	610 mm x 457 mm Maximum	BS EN 123 600
Conductors:	Minimum Width: 100 μ m \pm 25 μ m	
	Minimum Spacing: 100 μ m \pm 25 μ m	
Number of Layers:	24 Maximum	
Plated-through hole diameter:	0.30 mm Minimum finished	for component mounting
	0.30 mm Minimum drilled	via hole
Aspect ratio:	9 : 1 Maximum	

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